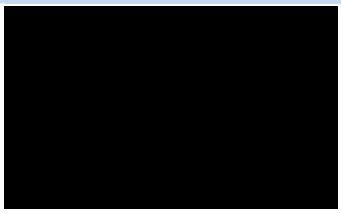
PDFN3×3-8L

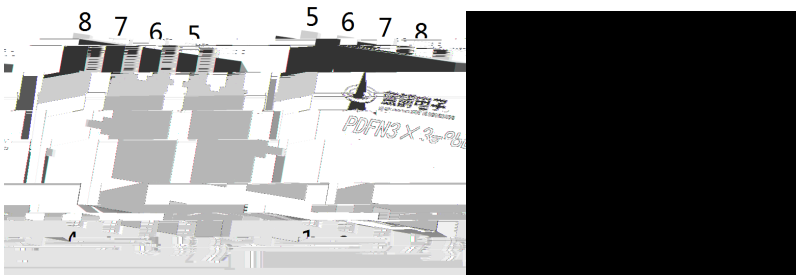
Complementary Enhancement MOSFET in a PDFN3×3-8L Plastic Package.

N-channel	P-channel
VDS(V)=20V	VDS(V)=-20V
ID=28A	ID=-25A
RDS(ON)<15mΩ(VGS=10V)	RDS(ON)<20mΩ(VGS=-10V)
RDS(ON)<20mΩ(VGS=4.5V)	RDS(ON)<25mΩ(VGS=-4.5V)
RDS(ON)<25mΩ(VGS=2.5V)	RDS(ON)<30mΩ(VGS=-2.5V)

HF Product.

Battery protection switch,Mobile device battery charging and discharging,Load switch

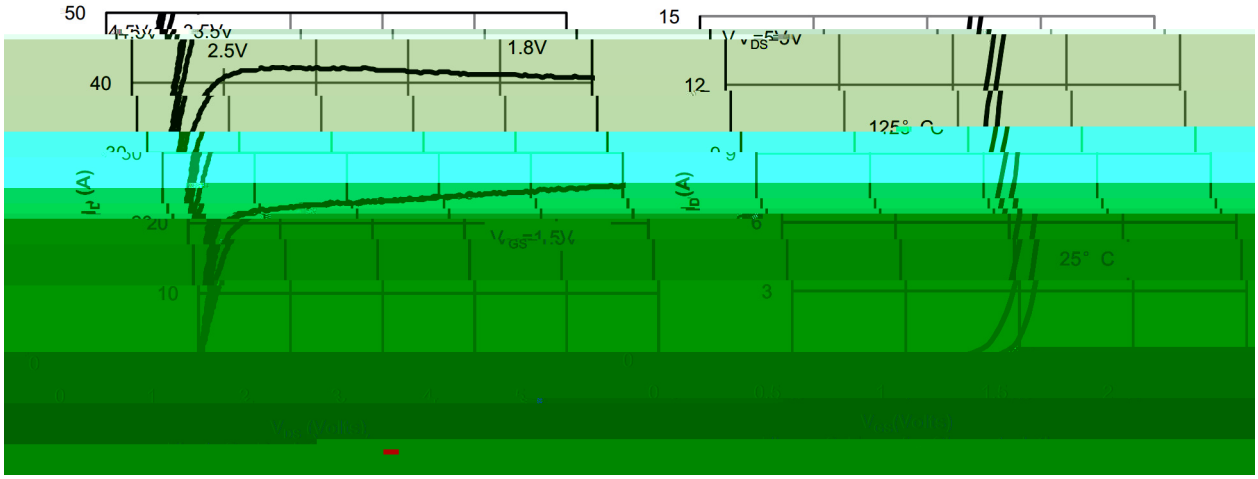


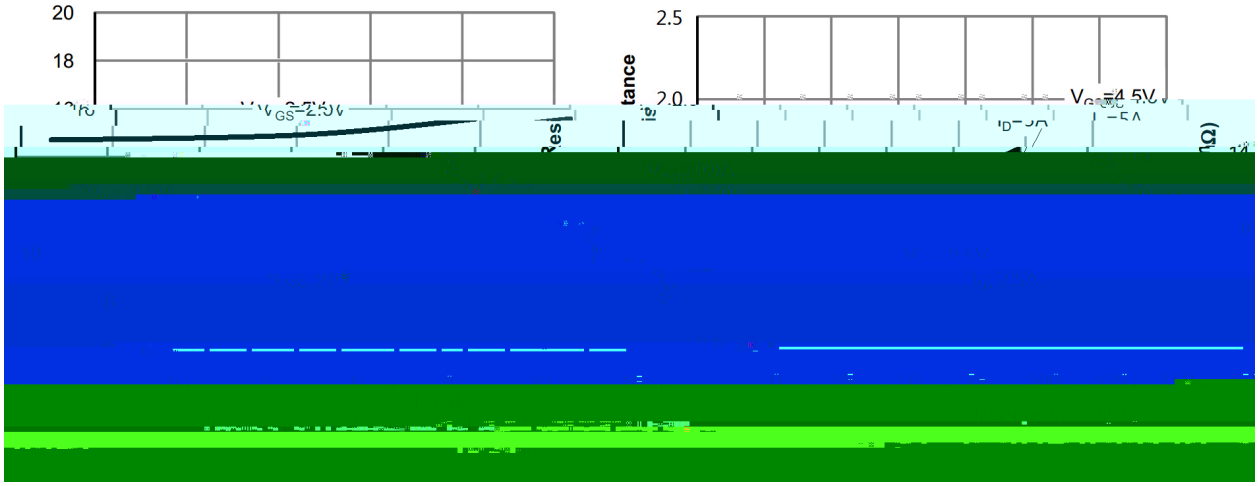


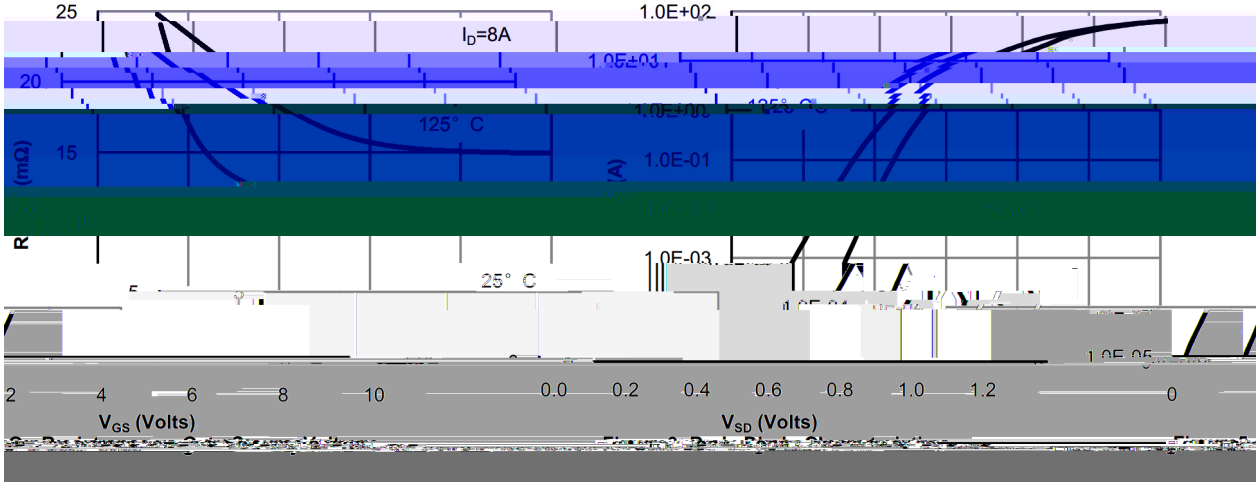
See Marking Instructions.

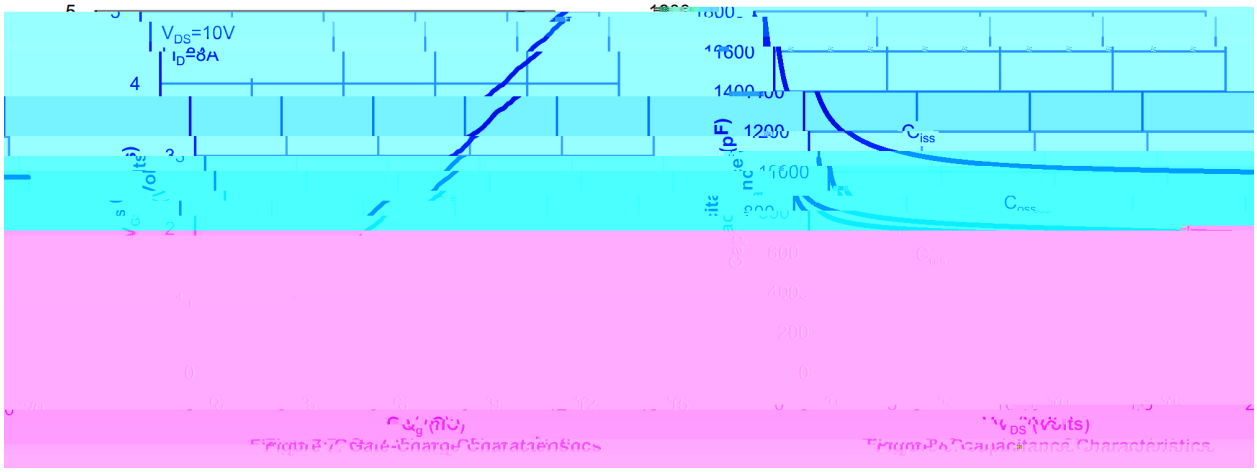
Parameter	Symbol	Rating		Unit
		N-channe	P-channell	
Drain-Source Voltage	V_{DSS}	±20		V
Gate-Source Voltage	V_{GSS}	±12		V
Continuous Drain Current	I_D (T_C=25)	28	-25	A
Pulsed Drain Current	I_{DM}	43	-38	A
Avalanche Current	I_{AS}	2.8	13.4	A
Avalanche energy L=0.5mH	E_{AS}	3.9	89.8	mJ
Power Dissipation	P_D (T_C=25)	18	17	W
Junction and Storage Temperature Range	T_J,T_{STG}	-55 to +150		
Maximum Junction-to-Ambient	$R_{\theta JA}$	95		/W
Maximum Junction-to-Case	$R_{\theta JC}$	7		/W

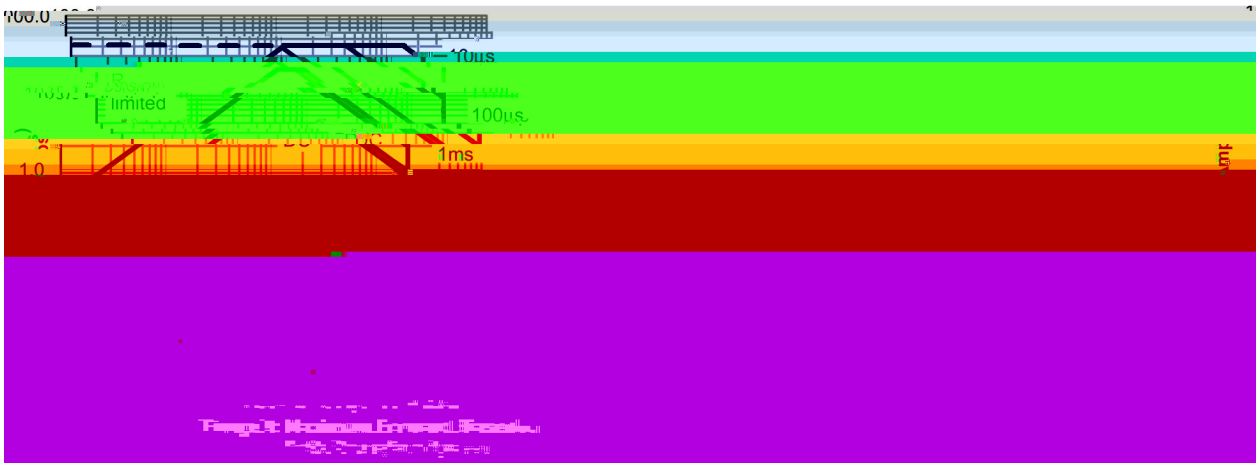
Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V	I_D=250μA	20	22.5		V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=20V	V_{GS}=0V			1.0	μA
Gate-Body leakage current	I_{GSS}	V_{GS}=±12V	V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}	I_D=250μA	0.5	0.7	1.2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V	I_D=10A		10	15	mΩ
		V_{GS}=4.5V	I_D=5A		11.5	20	mΩ
		V_{GS}=2.5V	I_D=2.5A		15	25	mΩ
Diode Forward Voltage	V_{SD}	V_{GS}=0V	I_S=1.0A		0.69	1.2	V
Input Capacitance	C_{iss}	V_{DS}=15V f=1.0MHz	V_{GS}=0V		1000		pF
Output Capacitance	C_{oss}				715		pF


50
40
2.5V
1.8V
V_{GS}=1.5V
15
12
125° C
25° C
3


20
18
2.5
2.0
V_{GS}=4.5V


25
I_D=8A
20
15
125° C
25° C
1.0E+02
1.0E+01
1.0E+00
1.0E-01
1.0E-03
2
4
6
8
10
0.0
0.2
0.4
0.6
0.8
1.0
1.2
V_{GS} (Volts)
V_{SD} (Volts)





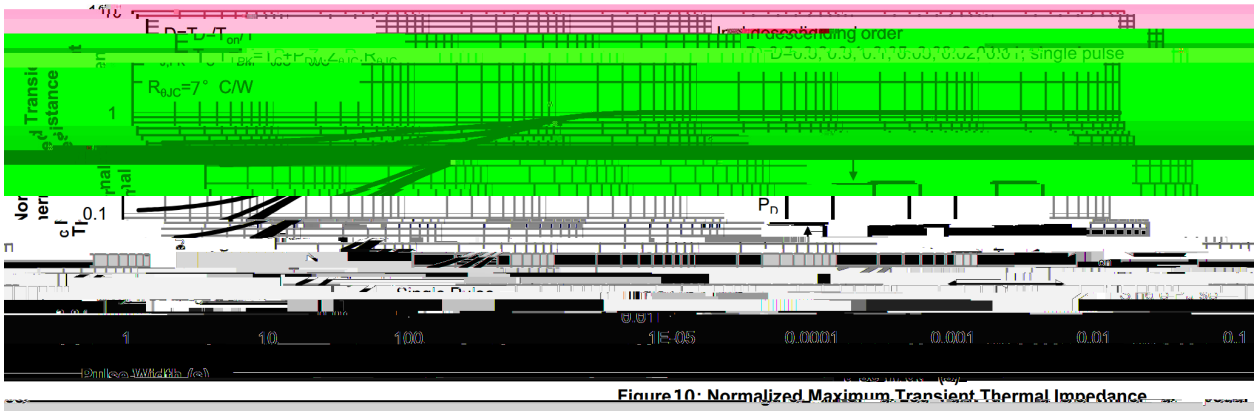
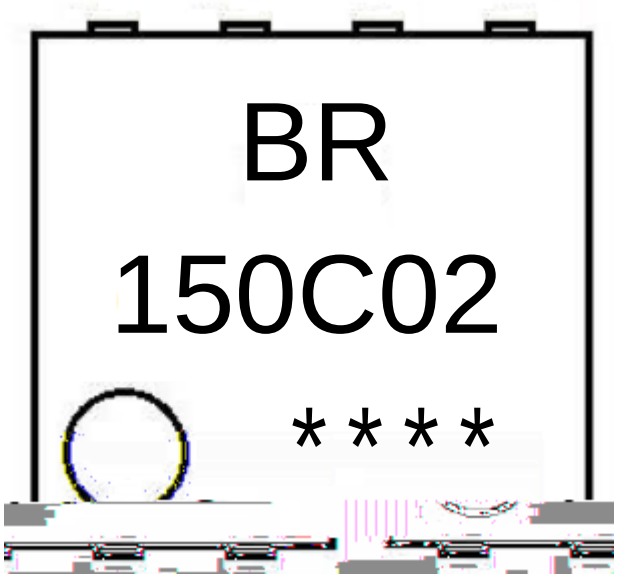


Figure 10: Normalized Maximum Transient Thermal Impedance

Rev.A Feb.-2023



BR

150C02

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Note:

BR:	Company Code
150C02:	Product Type Code
****:	Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)



				Note:
1	150	180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10 /sec.

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ REEL

Package Type	Units	Dimension	(unit mm